/ Descriptions

SOD-523

Silicon Diode in a SOD-523 Plastic Package.

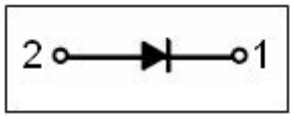
/ Features

Fast switching diodes,HF Product.

/ Applications

Small signal diode.

/ Equivalent Circuit

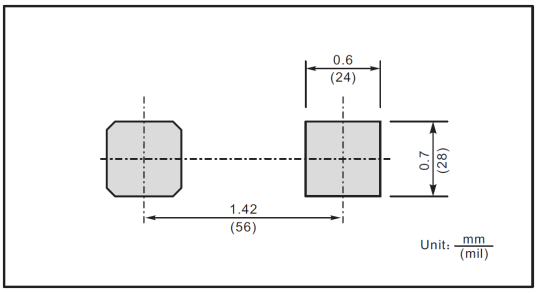


/ Pinning



PIN1:Cathode PIN2:Anode

The recommended mounting pad size



/ Marking

Marking	T4

Parameter	Symbol	Rating	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS voltage	V_{RMS}	75	V
Continuous Forward Current	I_F	150	mA
Non-reptitive Peak Forward Surge Current	I_{FSM} t=1ms	0.8	A
Power Dissipation	P_{tot}	150	mW
Junction Temperature	T_j	-55 150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Breakdown Voltage	$V_{(BR)R}$	I_R=1μA	75			V
		I_F=1mA			0.715	V
					0.855	

V V

/ Electrical Characteristic Curve

Fig.1 Power Derating Curve

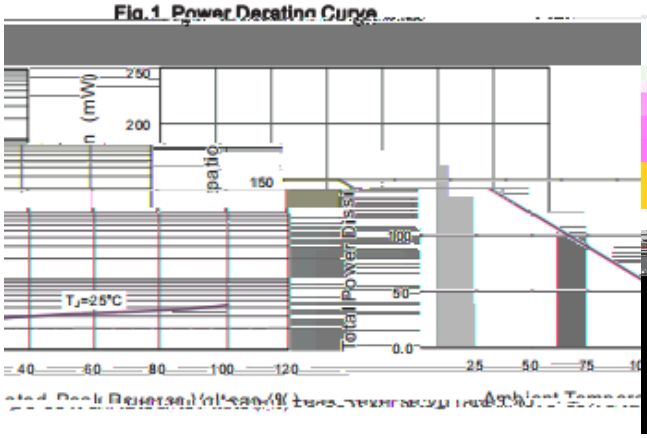
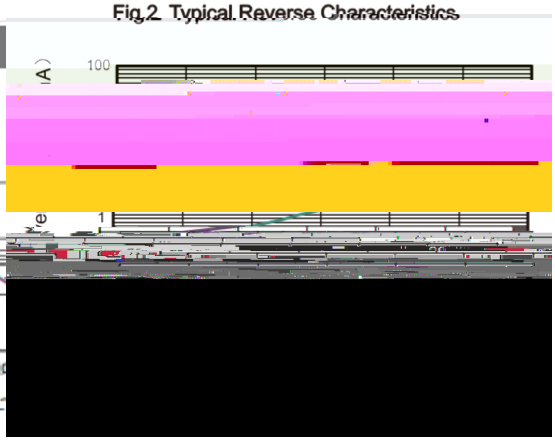
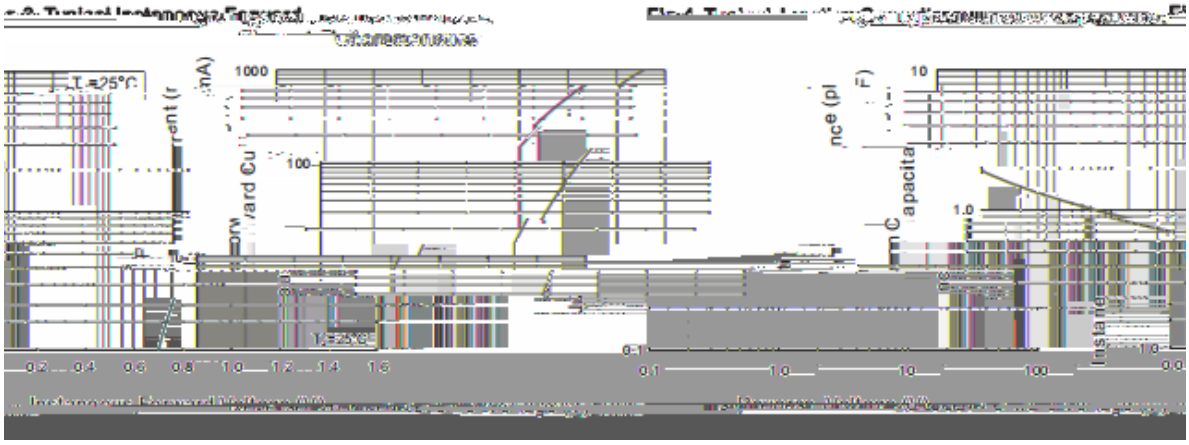


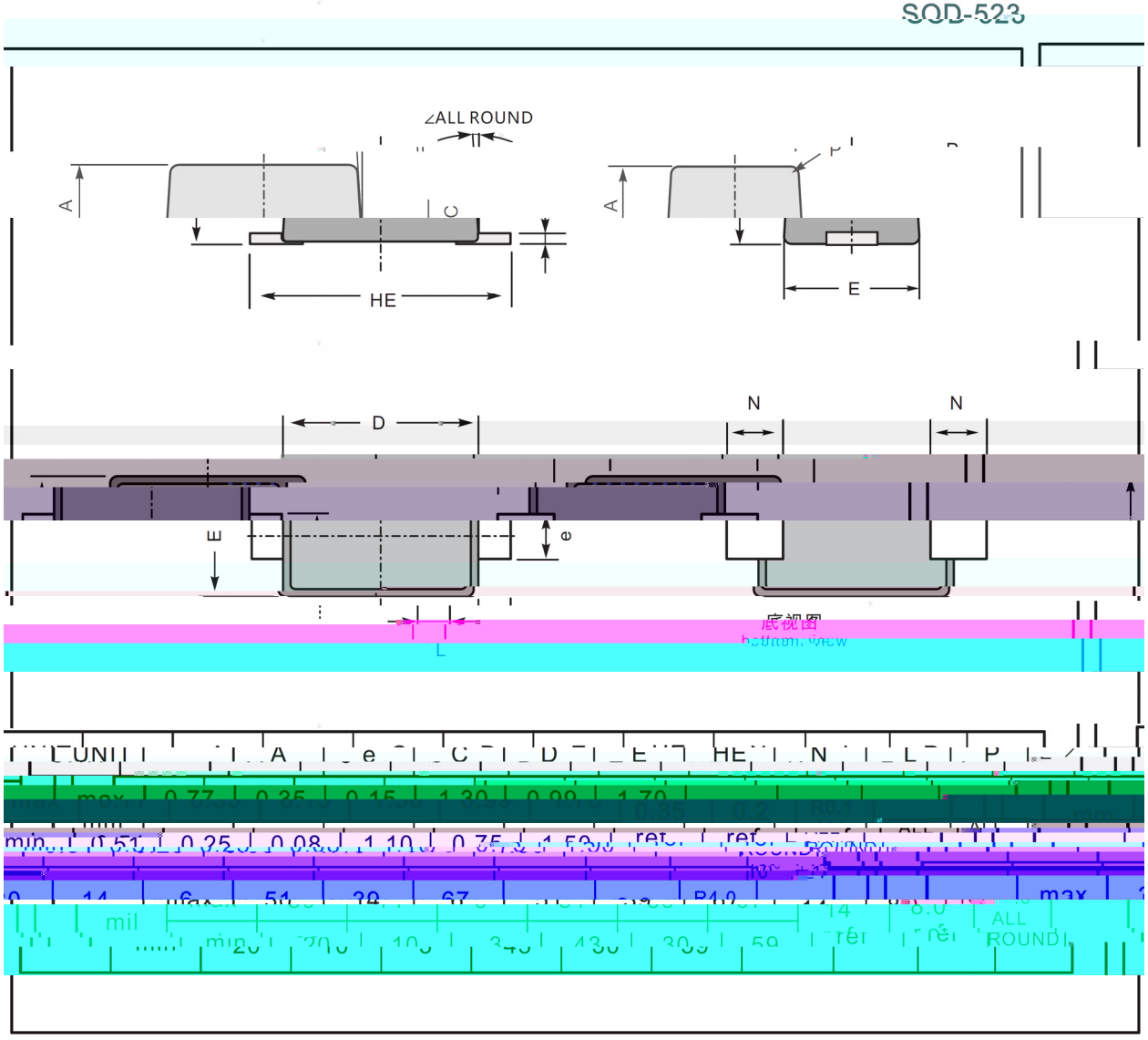
Fig.2 Typical Reverse Characteristics





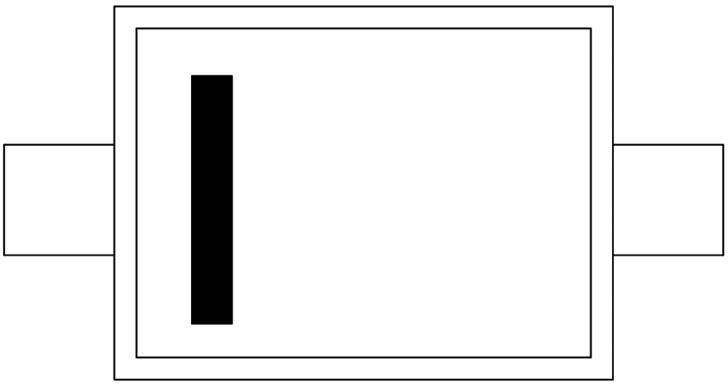
/ Package Dimensions

SOD-523



UNIT	A	e	C	D	E	HE	N	L	P
max	0.77	0.35	0.15	1.30	0.90	1.70		0.35	0.2
min	0.51	0.25	0.08	1.10	0.75	1.50	ref.	ref.	ROUND
max	30	14	6	51	28	67		14	max
mil									ALL
min	20	10	3	43	30	59	ref.	ref.	ROUND

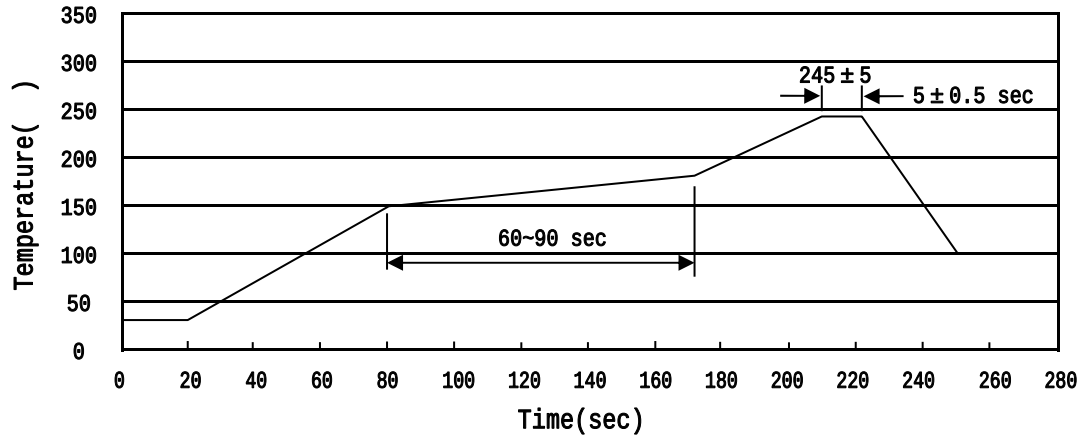
/ Marking Instructions



T4

T563.5ye

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



1		150	180		60	90sec;	Note: 1.Preheating:150~180 , Time:60~90sec.
2		245±5				5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3				2	10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOD-523	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices